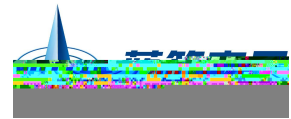


E	2016-5				
F	2020-4-27	1			
A	2022-3-29	all	BR Q 4R Q AEC-Q101 , Q 245±5°C 5±0.5sec 255±5°C 5± 0.5sec		



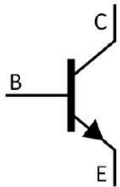
TO-252 NPN Silicon NPN transistor in a TO-252 Plastic Package.

$V_{CE(sat)}$, h_{FE} AEC-Q101

Low saturation voltage, excellent h_{FE} linearity and high h_{FE} , Qualified to AEC-Q101 Standards for High Reliability, HF Product.

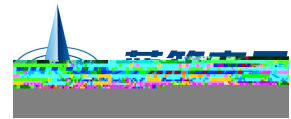
3

Output stage of 3 watts audio amplifier, voltage regulator, DC-DC converter and relay driver, Meet the stringent requirements of automotive applications.



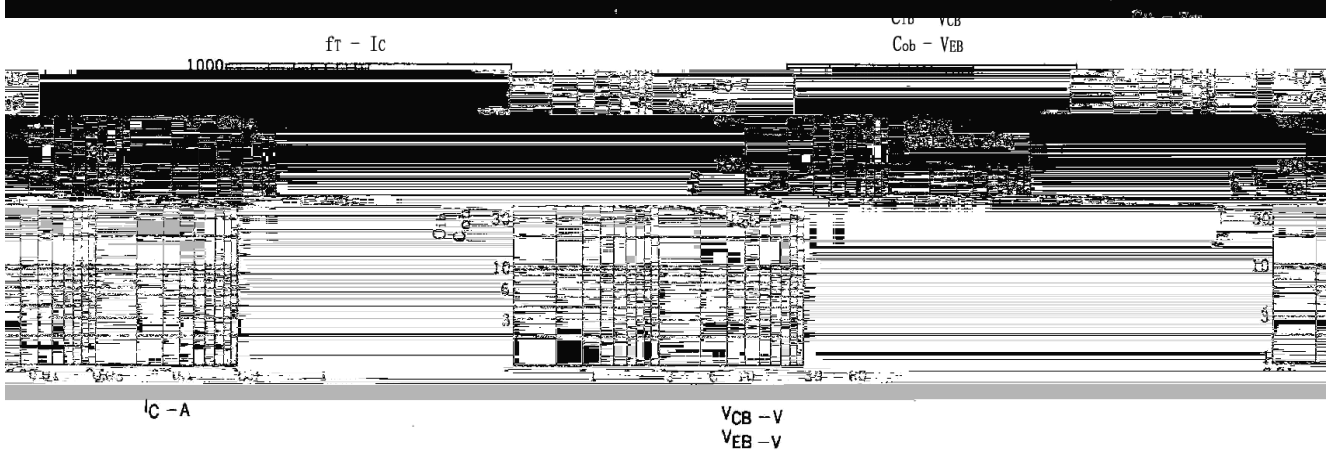
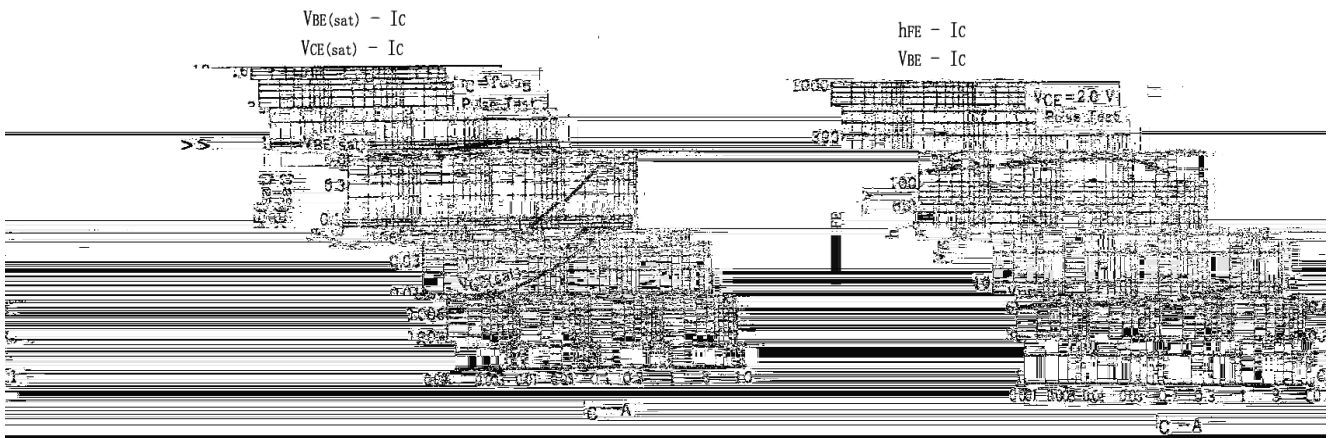
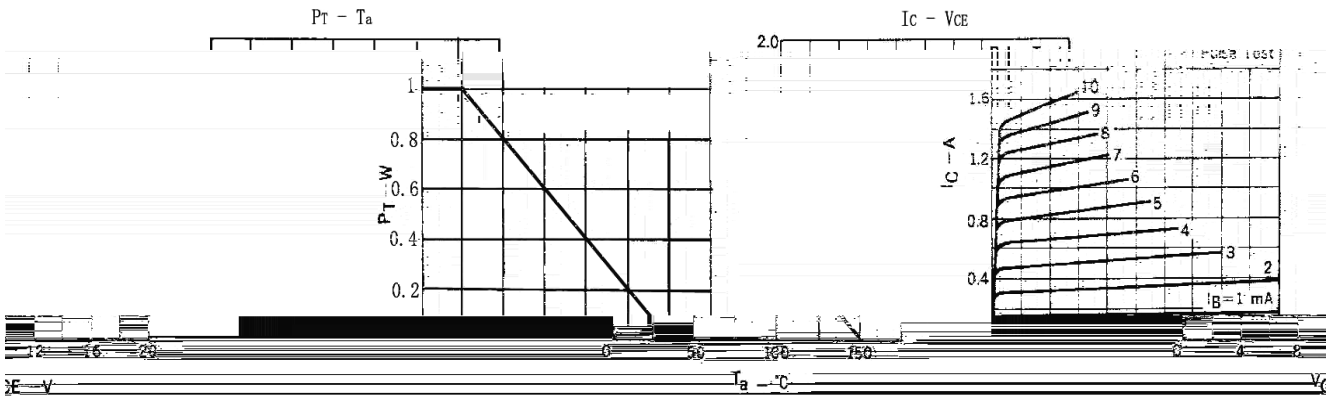
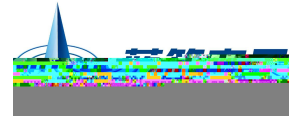
PIN1 Base PIN 2,4 Collector PIN 3 Emitter

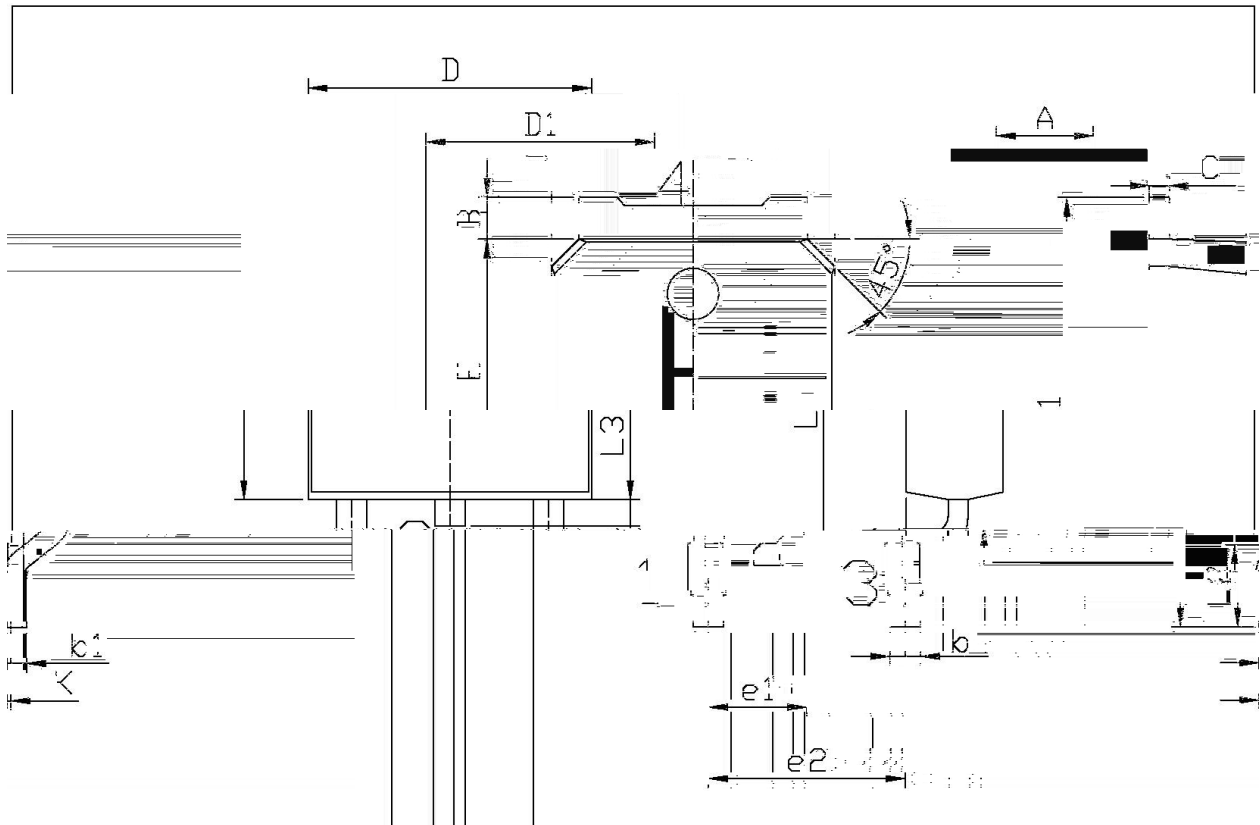
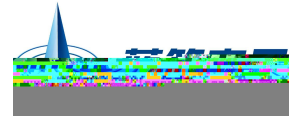
h_{FE} Classifications Symbol	R	Q	P	E
h_{FE} Range	60~120	100~200	160~320	200~400



Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	40	V
Collector to Emitter Voltage	V_{CEO}	30	V
Emitter to Base Voltage	V_{EBO}	5.0	V
Collector Current - Continuous	I_C	3.0	A
Collector Power Dissipation	P_C	1.0	W
	$P_{C(T_C=25^\circ C)}$	10	W
Junction Temperature	T_j	150	$^\circ C$
Storage Temperature Range	T_{stg}	-55~150	$^\circ C$

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector Cut-Off Current	I_{CBO}	$V_{CB}=30V$ $I_E=0$			1.0	μA
Emitter Cut-Off Current	I_{EBO}	$V_{EB}=3.0V$ $I_C=0$			1.0	μA
DC Current Gain	$h_{FE(1)}$	$V_{CE}=2.0V$ $I_C=1.0A$	60	160	400	
	$h_{FE(2)}$	$V_{CE}=2.0V$ $I_C=20mA$	30	150		
Collector to Emitter Saturation Voltage						V

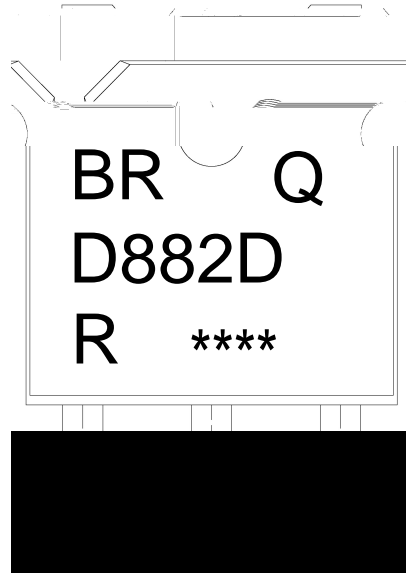
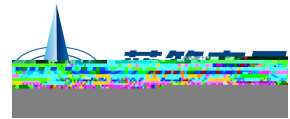




单位: mm

symbol	Dimensions In Millimeters		symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
A	2.20	2.40	L1	5.05	6.25
B	0.95	1.25	e1	2.24	2.34
b1	0.70	0.90	e2	4.43	4.73
L3	0.45	0.55	L2	9.85	10.35
C	0.45	0.55	L2	1.70	2.00
D	6.45	6.75	L3	0.60	0.90
D1	5.10	5.50	K	0.00	0.10

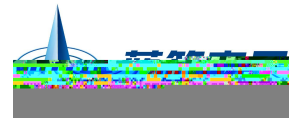
TP-252



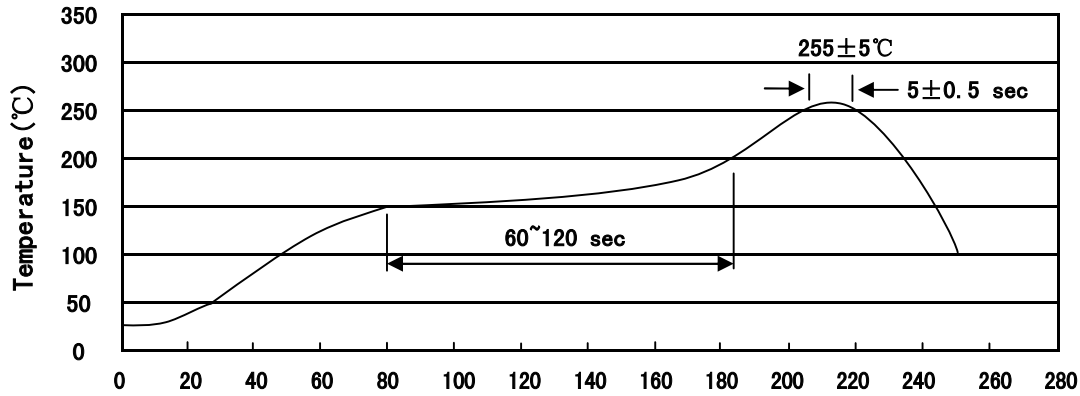
BR	
Q	
D882D	
R:	h_{FE}

Note:

- BR: Company Code
- Q: Automobile halogen-free product Code
- D882D: Product Type
- R: h_{FE} Classifications Symbol
- ****: Lot No. Code, code change with Lot No



Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 150~200°C，时间 60~120sec;
- 2、峰值温度 255±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2~10 /sec.

Note:

- 1.Preheating:150~200 , Time:60~120sec.
- 2.Peak Temp.:255±5 , Duration:5±0.5sec.
3. Cooling Speed: 2~10 /sec.

温度：260±5

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
TO-252	2,500	2	5,000	6	30,000	13" ×16	360×360×50	380×335×366

套管包装 / TUBE

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Tube 只/套管	Tubes/Inner Box 套管/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Tube 套管	Inner Box 盒	Outer Box 箱
TO-251/252	75	48	3,600	5	18,000	526×20.5×5.25	555×164×50	575×290×180